Slic™ Foil was developed for etching, milling and laser cutting SMT stencils. The microstructure and low residual stress ensure maximum performance and printability for every application.

**No. 1 Worldwide**

Our unique approach to metallurgy, from alloy selection to foil manufacturing and frame mounting, enables us to provide stencil materials that help control the printing process and reduce SMT defects:

- The industry's tightest thickness and flatness tolerances guarantee predictable area ratios and transfer efficiencies across the entire print area
- Stress-relieved foils resist heat distortion from laser cutting, offering superior flatness to optimize gasketing and registration
- Proprietary rolling and annealing processes deliver consistent materials for dependable and repeatable performance

**Quality Commitment**

- Every BlueRing team member is committed to providing the highest quality products and services
- BlueRing is ISO-9001 Certified
- Specialized manufacturing processes are continuously monitored and statistically controlled
- All product are inspect and verified prior to shipment

**Repeatability**

Slic™ is the world's first SS alloy developed specifically for laser-cut SMT stencils. Harder and more durable than standard SS, Slic™ provides longer life, especially in demanding production processes. Repeatability is the key to optimizing print performance:

- Thickness tolerance of +/- 2% is the tightest in the industry, with > 6σ repeatability
- Controlled surface roughness of < 0.15μm maintains paste rolling characteristics from stencil to stencil
- Uniform grain structure and low residual stress ensure consistent response to tensioning, chemical etching, laser cutting and printing processes

**Specifications**

- **Gauges**: 0.02 to 0.500 (0.8 mil to 20 mil)
- **Sizes**: Widths up to 690mm
- **Availability**: Worldwide

<table>
<thead>
<tr>
<th></th>
<th>Slic</th>
<th>UltraSlic FG</th>
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</thead>
<tbody>
<tr>
<td>Miniaturised or high-density assembly</td>
<td>*</td>
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<tr>
<td>Area ratios &lt;0.60</td>
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<tr>
<td>General SMT, lead pitches ≥ 0.5mm, leadless pitches ≥ 1.0mm</td>
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<tr>
<td>Stepped stencil for μBGA, CSP, QFN, BTC</td>
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<td>*</td>
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<tr>
<td>Uniform foil thickness ≥150μm</td>
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<tr>
<td>Powder Size Type: 5, 6</td>
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<tr>
<td>Powder Size Type: 3, 4</td>
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</tbody>
</table>

**Ideal for Standard Stencil Steps**

- **Top side**: connectors, shields, larger SMT components
- **Bottom side**: cavity relief for labels and topographical features

**Standard SS Microstructure**

**Grain Size**: 15-30μm

**Slic™ Microstructure Grain**

**Grain Size**: 7-11μm

1-866-763-3873

www.blueringstencils.com